

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6910196

| | |
|---|---|
| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| SEQUENCE: | 3 |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| SUNEDISON SEMICONDUCTOR LIMITED (UEN201334164H) | 06/06/2018 |
| RECEIVING PARTY DATA | |
| Name: | GLOBALWAFERS CO., LTD. |
| Street Address: | NO. 8. INDUSTRIAL EAST ROAD |
| Internal Address: | SCIENCE-BASED INDUSTRIAL PARK |
| City: | HSINCHU |
| State/Country: | TAIWAN |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 17471641 |
| CORRESPONDENCE DATA | |
| Fax Number: | (314)612-2307 |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Phone: | 314-621-5070 |
| Email: | USpatents@atllp.com, clager@atllp.com |
| Correspondent Name: | PATENT DOCKET DEPARTMENT ARMSTRONG TEASDALE LLP |
| Address Line 1: | 7700 FORSYTH BOULEVARD |
| Address Line 2: | SUITE 1800 |
| Address Line 4: | ST. LOUIS, MISSOURI 63105 |
| ATTORNEY DOCKET NUMBER: | 28744-5409 (151087.13) |
| NAME OF SUBMITTER: | NICHOLAS A. KEPPEL |
| SIGNATURE: | /Nicholas A. Keppel/ |
| DATE SIGNED: | 09/10/2021 |
| Total Attachments: 7 | |
| source=Executed Assignment to GWC-42636306#page1.tif | |
| source=Executed Assignment to GWC-42636306#page2.tif | |
| source=Executed Assignment to GWC-42636306#page3.tif | |
| source=Executed Assignment to GWC-42636306#page4.tif | |

source=Executed Assignment to GWC-42636306#page5.tif
source=Executed Assignment to GWC-42636306#page6.tif
source=Executed Assignment to GWC-42636306#page7.tif

ASSIGNMENT

This Assignment is made by and among SunEdison Semiconductor Limited, a company organized and existing under the laws of Singapore ("SSL"), MEMC Japan Limited, a company organized and existing under the laws of Japan ("MEMC Japan"), and MEMC Electronic Materials, S.P.A., a company organized and existing under the laws of Italy ("MEMC EM", and collectively with SSL and MEMC Japan, the "Assignors"), and GlobalWafers Co., Ltd., a company organized and existing under the laws of Taiwan and having its registered address at No. 8, Industrial East Road, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereinafter referred to as "Assignee");

WHEREAS, on December 31, 2016, Assignors entered into certain IP Transfer Agreements with Assignee;

WHEREAS, the parties hereto desire to memorialize, *nunc pro tunc*, the assignment and ownership of all Assigned IP (defined below) for, among other things, recordal purposes with certain patent administration bodies, such as the United States Patent and Trademark Office; and

WHEREAS, Assignors acknowledge that payment in full from Assignee for all Assigned IP has heretofore been paid.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignors have agreed to and do hereby sell, assign and transfer, and confirm the sale, assignment and transfer, unto Assignee all of their rights, title and interest throughout the world, including without limitation, the right to sue and recover for any past infringements, in and to the Listed IP, any other applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on any Listed IP, any corresponding patent or patent applications filed in any country based in whole or in part on, and/or claiming priority from, any Listed IP, any patents (including extensions thereof) of any country based in whole or in part on, and/or claiming priority from, any Listed IP, and all of the inventions described in the Listed IP and all of the aforementioned patents and patent applications (all of the foregoing, collectively, the "Assigned IP");

TO BE HELD AND ENJOYED by said Assignee, its successors and assigns, as fully and entirely as the Assigned IP would have been held and enjoyed by Assignors had no assignment of said interest been made.

EACH ASSIGNOR hereby agrees that it will do, execute and deliver, or will cause to be done, executed and delivered, all such further lawful acts, transfers, assignments and conveyances, powers of attorney and assurances for the better assuring, conveying and confirming unto Assignee, all of such Assignor's rights, title and interest in and to the Assigned IP hereby transferred, assigned and conveyed, as Assignee may reasonably require.

[Signature Pages Follow]

IN WITNESS WHEREOF, the undersigned have caused these presents to be executed by their respective officers thereunto duly authorized this 6 day of June, 2018.

Assignor:

SUNEDISON SEMICONDUCTOR LIMITED

By: *Paul Markowitz*

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of SUNEDISON SEMICONDUCTOR LIMITED, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Damiani
Notary Public

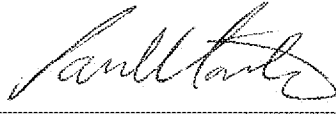
My Commission Expires:

July 20, 2018



Assignor:

MEMC JAPAN LTD

By: 


Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

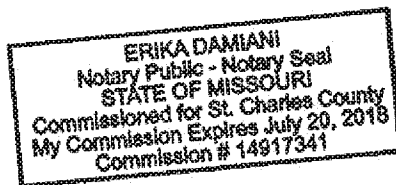
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC JAPAN LTD, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

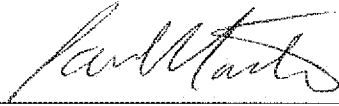
My Commission Expires:

July 20, 2018



Assignor:

MEMC ELECTRONIC MATERIALS S.P.A.

By: 


Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

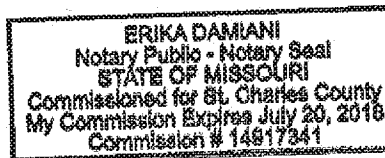
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC ELECTRONIC MATERIALS S.P.A., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

My Commission Expires:

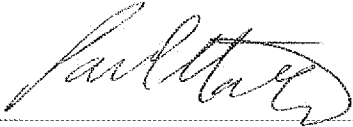
July 20, 2018



For and on behalf of GlobalWafers Co., Ltd.

Assignee:

GLOBALWAFERS CO., LTD.

By: 

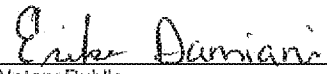
Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)
COUNTY OF St. Charles

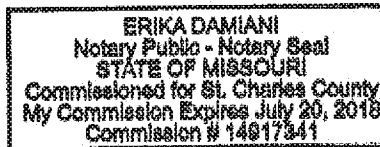
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of GLOBALWAFERS CO., LTD., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

My Commission Expires:

July 20, 2018



SCHEDULE A

| TITLE | Country | Application Number | Filing Date | Publication Number | Publication Date | Patent Number | Issue Date |
|---|---------|--------------------|-------------|--------------------|------------------|------------------|-------------|
| PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE | NO | 20073126 | 18-Jun-2007 | | | | |
| PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE | CN | 200580039715.7 | 19-May-2007 | CN101065324A | 31-Oct-2007 | ZL200580039715.7 | 16-Mar-2011 |
| PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE | IN | 3611/DELNP/2007 | 15-May-2007 | 3611/DELNP/2007A | 31-Aug-2007 | 276554 | 25-Oct-2016 |
| PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE | SG | 200703413-5 | 19-Apr-2007 | | | 133641 | 29-Jul-2011 |
| PROCESS FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE | US | 11/719688 | 21-Aug-2007 | 2008-0314728 | 25-Dec-2008 | 7879198 | 1-Feb-2011 |
| PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE | SG | 200907702-5 | 19-Nov-2009 | 0158071 | 29-Jan-2010 | 158071 | 28-Jun-2013 |
| PROCESS FLOW FOR MANUFACTURING SEMICONDUCTOR ON INSULATOR STRUCTURES IN PARALLEL | US | 15/435428 | 17-Feb-2017 | 2017-0243781 | 24-Aug-2017 | 9831115 | 28-Nov-2017 |
| SEMICONDUCTOR ON INSULATOR STRUCTURE COMPRISING A BURIED HIGH RESISTIVITY LAYER | WO | PCT/US2017/017756 | 14-Feb-2017 | WO 2017/142849 | 24-Aug-2017 | | |
| HIGH RESISTIVITY SILICON-ON-INSULATOR SUBSTRATE COMPRISING A CHARGE TRAPPING LAYER FORMED ON A SUBSTRATE WITH A ROUGH SURFACE | WO | PCT/US2017/015813 | 31-Jan-2017 | WO 2017/142704 | 24-Aug-2017 | | |
| HIGH RESISTIVITY SINGLE CRYSTAL SILICON INGOT AND WAFER HAVING IMPROVED MECHANICAL STRENGTH | WO | PCT/US2017/036061 | 6-Jun-2017 | WO 2017/214084 | 14-Dec-2017 | | |
| HIGH RESISTIVITY SINGLE CRYSTAL SILICON INGOT AND WAFER HAVING IMPROVED MECHANICAL STRENGTH | TW | 106119035 | 8-Jun-2017 | 201809377 | 16-Mar-2018 | | |
| HIGH RESISTIVITY SILICON-ON-INSULATOR SUBSTRATE HAVING ENHANCED CHARGE TRAPPING EFFICIENCY | TW | 106136283 | 23-Oct-2017 | | | | |
| HIGH RESISTIVITY SILICON-ON-INSULATOR SUBSTRATE HAVING ENHANCED CHARGE TRAPPING EFFICIENCY | US | 15/727723 | 9-Oct-2017 | 2018-0114720 | 26-Apr-2018 | | |
| HIGH RESISTIVITY SILICON-ON-INSULATOR SUBSTRATE HAVING ENHANCED CHARGE TRAPPING EFFICIENCY | WO | PCT/US2017/055722 | 9-Oct-2017 | WO 2018/080772 | 3-May-2018 | | |

PATENT